

DRAM

**256K x 16 DYNAMIC
RAM**

EDO PAGE MODE

FEATURES

- Industry-standard x 16 pinouts and timing functions.
- Single 5V ($\pm 10\%$) power supply.
- All device pins are TTL-compatible.
- 512-cycle refresh in 8ms.
- Refresh modes: RAS only, CAS BEFORE RAS (CBR) and HIDDEN.
- Extended data-out (EDO) PAGE MODE access cycle.
- BYTE WRITE and BYTE READ access cycles.

OPTION

TIMING	EDO	MARKING
22ns	125 MHz	-22
25ns	100 MHz	-25
28ns	100 MHz	-28
35ns	83 MHz	-35
45ns	60 MHz	-45
50ns	50 MHz	-50

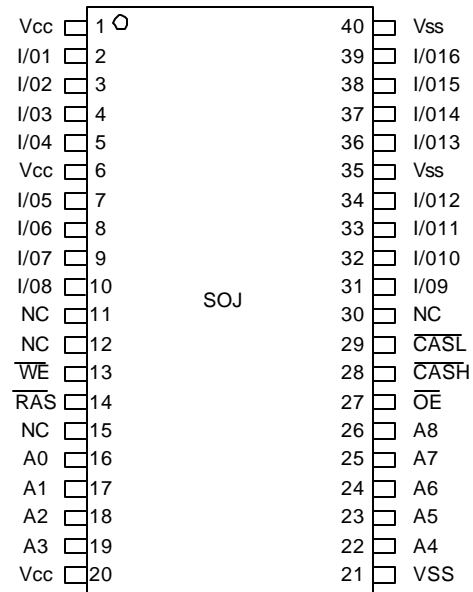
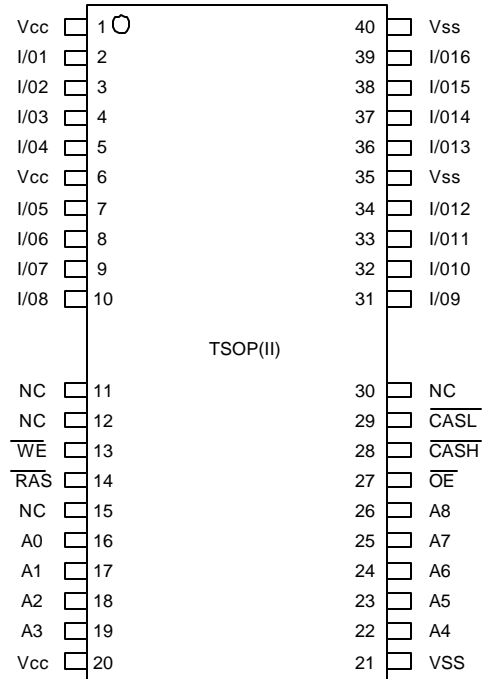
PACKAGE	MARKING
SOJ	J
TSOP(II)	S

GENERAL DESCRIPTION

The T224162B is a randomly accessed solid state memory containing 4,194,304 bits organized in a x16 configuration. The T224162B has both BYTE WRITE and WORD WRITE access cycles via two CAS pins. It offers Fast Page mode with Extended Data Output.

The T224162B CAS function and timing are determined by the first CAS to transition low and by the last to transition back high. Use only one of the two CAS and leave the other staying high during WRITE will result in a BYTE WRITE. CASL transiting low in a WRITE cycle will write data into the lower byte (IO1~IO8), and CASH transiting low will write data into the upper byte (IO9~16).

PIN ASSIGNMENT (Top View)



ABSOLUTE MAXIMUM RATINGS*

Voltage on Any pin Relative to VSS..... -1V to +7V
 Operating Temperature, Ta (ambient) ..0°C to +70°C
 Storage Temperature (plastic)..... -55°C to +150°C
 Power Dissipation
 1.0W
 Short Circuit Output Current..... 50mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS AND RECOMMENDED OPERATING CONDITIONS

(0°C ≤ Ta ≤ 70°C; VCC = 5V ± 10 % unless otherwise noted)

DESCRIPTION	CONDITIONS	SYM.	MIN	MAX	UNITS	NOTES
Supply Voltage		V _{CC}	4.5	5.5	V	1
Supply Voltage		V _{SS}	0	0	V	
Input High (Logic) voltage		V _{IH}	2.4	V _{CC} +1	V	1
Input Low (Logic) voltage		V _{IL}	-1.0	0.8	V	1
Input Leakage Current	0V ≤ V _{IN} ≤ 7V	I _{LI}	-10	10	uA	
Output Leakage Current	0V ≤ V _{OUT} ≤ 7V Output(s) disabled	I _{LO}	-10	10	uA	
Output High Voltage	I _{OH} = -5 mA	V _{OH}	2.4	V _{CC}	V	
Output Low Voltage	I _{OL} = 4.2 mA	V _{OL}	0	0.4	V	

Note: 1.All Voltages referenced to Vss

DESCRIPTION	CONDITIONS	SYM.	MAX						UNITS	NOTES
			-22	-25	-28	-35	-45	-50		
Operating Current	RAS, CAS cycling, t _{RC} = min	I _{CC1}	190	180	170	150	130	110	mA	1,2
Standby Current	TTL interface, RAS, CAS = V _{IH} , D _{OUT} = High-Z	I _{CC2}	4	4	4	4	4	4	mA	
	CMOS interface, RAS, CAS > V _{CC} -0.2V		2	2	2	2	2	2	mA	
RAS-only refresh Current	t _{RC} = min	I _{CC3}	190	180	170	150	130	110	mA	2
Standby Current	RAS = V _{IH} , CAS = V _{IL}	I _{CC5}	5	5	5	5	5	5	mA	1
CAS Before RAS Refresh Current	t _{RC} = min	I _{CC6}	190	180	170	150	130	110	mA	
EDO Page Mode Current	t _{PC} = min	I _{CC7}	190	180	170	150	130	110	mA	1,3

Note: 1. I_{CC} depends on output load condition when the device is selected.

I_{CC} max is specified at the output open condition.

2. Address can be changed twice or less while RAS = V_{IL}.

3. Address can be changed once or less while CAS = V_{IH}.

CAPACITANCE

(Ta = 25°C, Vcc = 5V ± 10 %)

Parameter	Symbol	Typ	Max	Unit	Notes
Input Capacitance (address)	C _{I1}	-	5	pF	1
Input Capacitance (clocks)	C _{I2}	-	7	pF	1
Output Capacitance (data-in, data-out)	C _{I/O}	-	10	pF	1

Note: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

AC ELECTRICAL CHARACTERISTICS (note 14)

(Ta = 0 to 70°C, Vcc = 5V ± 10 %, Vss = 0V)

Input timing reference levels: 0.8V, 2.4V

Test Conditions (note 29)

 Output Load: 2TTL gate + C_L (50pF)

AC CHARACTERISTICS PARAMETER	SYM	-22		-25		-28		-35		-45		-50		UNIT	Notes
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
Read or Write Cycle Time	t _{RC}	42		45		48		65		85		100		ns	
Read Write Cycle Time	t _{RWC}	62		65		70		95		115		135		ns	
EDO-Page-Mode Read or Write Cycle Time	t _{PC}	8		10		10		12		16		20		ns	22
EDO-Page-Mode Read-Write Cycle Time	t _{PCM}	30		32		34		40		46		57		ns	22
Access Time From $\overline{\text{RAS}}$	t _{RAC}		22		25		28		35		45		50	ns	4
Access Time From $\overline{\text{CAS}}$	t _{CAC}		7		7		7		9		11		13	ns	5,20
Access Time From $\overline{\text{OE}}$	t _{OAC}		8		8		8		9		11		13	ns	13,20
Access Time From Column Address	t _{AA}		11		12		13		15		19		23	ns	
Access Time From $\overline{\text{CAS}}$ Precharge	t _{ACP}		13		14		15		18		22		26	ns	20
$\overline{\text{RAS}}$ Pulse Width	t _{RAS}	22	10K	25	10K	28	10K	35	10K	45	10K	50	10K	ns	
$\overline{\text{RAS}}$ Pulse Width (EDO Page Mode)	t _{RASC}	22	100K	25	100K	28	100K	35	100K	45	100K	50	100K	ns	
$\overline{\text{RAS}}$ Hold Time	t _{RSH}	7		7		7		9		11		13		ns	27
$\overline{\text{RAS}}$ Precharge Time	t _{RP}	15		15		17		25		35		37		ns	
$\overline{\text{CAS}}$ Pulse Width	t _{CAS}	4	10K	4	10K	4	10K	4	10K	6	10K	8	10K	ns	26
$\overline{\text{CAS}}$ Hold Time	t _{CSH}	19		20		22		30		40		50		ns	19
$\overline{\text{CAS}}$ Precharge Time (EDO Page Mode)	t _{CP}	3		3		3		3		5		6		ns	23
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Delay Time	t _{RCD}	9	15	10	17	10	19	10	26	10	34	19	37	ns	7,18
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ Precharge Time	t _{CRP}	3		3		3		3		5		5		ns	19

AC ELECTRICAL CHARACTERISTICS (continued)

AC CHARACTERISTICS PARAMETER	SYM	-22		-25		-28		-35		-45		-50		UNIT	Notes
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
Row Address Setup Time	t _{ASR}	0		0		0		0		0		0		ns	
Row Address Hold Time	t _{RAH}	5		5		5		5		5		5		ns	
RAS to Column Address Delay Time	t _{RAD}	8	11	8	12	8	13	8	20	8	26	10	29	ns	8
Column Address Setup Time	t _{ASC}	0		0		0		0		0		0		ns	18
Column Address Hold Time	t _{CAH}	4		4		4		4		6		7		ns	18
Column Address Hold Time (Reference to $\overline{\text{RAS}}$)	t _{AR}	17		19		21		30		40		45		ns	
Column Address to $\overline{\text{RAS}}$ Lead Time	t _{RAL}	11		12		13		15		19		23		ns	
Read Command Setup Time	t _{RCS}	0		0		0		0		0		0		ns	15,18
Read Command Hold Time Reference to $\overline{\text{CAS}}$	t _{RCH}	0		0		0		0		0		0		ns	9,15, 19
Read Command Hold Time Reference to $\overline{\text{RAS}}$	t _{RRH}	0		0		0		0		0		0		ns	9
$\overline{\text{CAS}}$ to Output in Low-Z	t _{CLZ}	3		3		3		3		3		3		ns	20
Output Buffer Turn-off Delay From $\overline{\text{CAS}}$ or $\overline{\text{RAS}}$	t _{OFF1}	3		3		3		3	15	3	15	3	15	ns	10,17, 20
Output Buffer Turn-off to $\overline{\text{OE}}$	t _{OFF2}		8		8		8		8		8		8	ns	17,28
Write Command Setup Time	t _{WCS}	0		0		0		0		0		0		ns	11,15, 18
Write Command Hold Time	t _{WCH}	4		4		4		4		6		7		ns	15,27
Write Command Hold Time (Reference to $\overline{\text{RAS}}$)	t _{WCR}	19		19		21		30		46		51		ns	15
Write Command Pulse Width	t _{WP}	4		4		4		4		6		8		ns	15
Write Command to $\overline{\text{RAS}}$ Lead Time	t _{RWL}	6		6		6		7		9		10		ns	15
Write Command to $\overline{\text{CAS}}$ Lead Time	t _{CWL}	5		5		5		7		9		11		ns	15,19
Data-in Setup Time	t _{DS}	0		0		0		0		0		0		ns	12,20
Data-in Hold Time	t _{DH}	4		4		4		4		6		7		ns	12,20
Data-in Hold Time (Reference to $\overline{\text{RAS}}$)	t _{DHR}	19		19		21		30		40		45		ns	
$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ Delay Time	t _{RWD}	31		34		37		51		61		70		ns	11

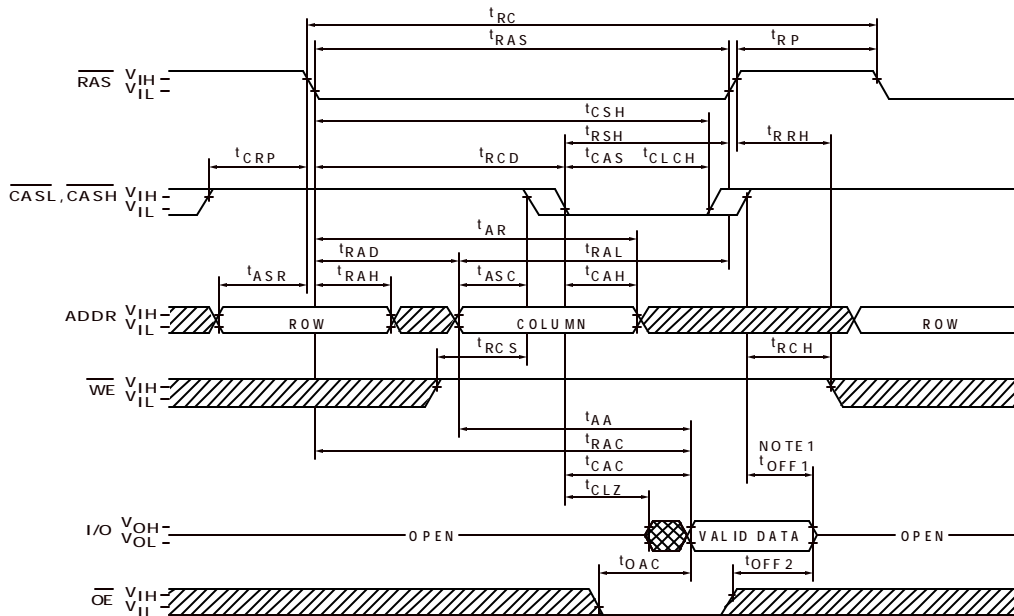
AC ELECTRICAL CHARACTERISTICS (continued)

AC CHARACTERISTICS PARAMETER	SYM	-22		-25		-28		-35		-45		-50		UNIT	Notes
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
Column Address to $\overline{\text{WE}}$ Delay Time	t_{AWD}	21		21		24		31		35		43		ns	11
$\overline{\text{CAS}}$ to $\overline{\text{WE}}$ Delay Time	t_{CWD}	17		17		18		25		27		33		ns	11,18
Transition Time (rise or fall)	t_{T}	1.5	50	1.5	50	1.5	50	2.5	50	2.5	50	2.5	50	ns	2,3
Refresh Period (512 cycles)	t_{REF}		8		8		8		8		8		8	ms	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Precharge Time	t_{RPC}	10		10		10		10		10		10		ns	
$\overline{\text{CAS}}$ Setup Time (CBR REFRESH)	t_{CSR}	5		5		5		10		10		10		ns	1,18
$\overline{\text{CAS}}$ Hold Time (CBR REFRESH)	t_{CHR}	7		7		7		10		10		10		ns	1,19
$\overline{\text{OE}}$ Hold Time From $\overline{\text{WE}}$ During Read-Modify-Write Cycle	t_{OEH}	4		4		4		4		6		8		ns	16
$\overline{\text{OE}}$ Low to $\overline{\text{CAS}}$ High Setup Time	t_{OES}	4		4		4		4		5		5		ns	
$\overline{\text{OE}}$ High Hold Time From $\overline{\text{CAS}}$ High	t_{OEHC}	2		2		2		2		2		2		ns	
$\overline{\text{OE}}$ High Pulse Width	t_{OEP}	2		2		2		2		2		2		ns	
$\overline{\text{OE}}$ Setup Prior to $\overline{\text{CAS}}$ During Hidden Refresh Cycle	t_{ORD}	0		0		0		0		0		0		ns	
Last $\overline{\text{CAS}}$ Going Low to First $\overline{\text{CAS}}$ Returning High	t_{CLCH}	4		4		4		4		6		8		ns	21
Data Output Hold After $\overline{\text{CAS}}$ Returning Low	t_{COH}	3		3		3		3		4		5		ns	
Output Disable Delay From $\overline{\text{WE}}$	t_{WHZ}	3	6	3	7	3	7	3	7	3	7	3	9	ns	

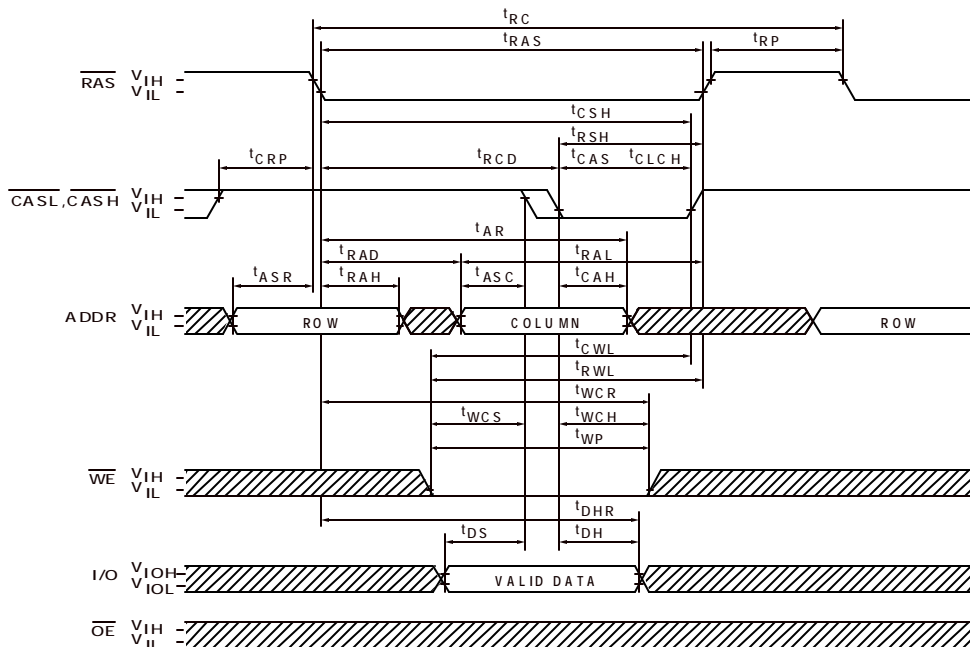
Notes:

1. Enables on-chip refresh and address counters.
2. $V_{IH}(2.4V)$ and $V_{IL}(0.8V)$ are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} (2.4V) and V_{IL} (0.8V).
3. In addition to meet the transition rate specification, all input signals must transit between V_{IH} and V_{IL} in a monotonic manner.
4. Assume that $t_{RCD} < t_{RCD(max)}$. If t_{RCD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by the amount that t_{RCD} exceeds the value shown.
5. Assume that $t_{RCD} \geq t_{RCD(max)}$.
6. If \overline{CAS} is low at the falling edge of \overline{RAS} , data-out will be maintained from the previous cycle. To initiate a new cycle and clear the data-out buffer, \overline{CAS} and \overline{RAS} must be pulsed high.
7. Operation within the $t_{RCD(max)}$ limit ensures that $t_{RAC(max)}$ can be met. $t_{RCD(max)}$ is specified as a reference point only; if t_{RCD} is greater than the specified $t_{RCD(max)}$ limit, access time is controlled by t_{CAC} .
8. Operation within the t_{RAD} limit ensures that $t_{RAC(max)}$ can be met. $t_{RAD(max)}$ is specified as a reference point only; if t_{RAD} is greater than the specified $t_{RAD(max)}$ limit, access time is controlled by t_{AA} .
9. Either t_{RCH} or t_{RRH} must be satisfied for a READ cycle.
10. $t_{OFF1(max)}$ defines the time at which the output achieves the open circuit condition; it is not a reference to V_{OH} or V_{OL} .
11. t_{WCS} , t_{RWD} , t_{AWD} and t_{CWD} are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycles only. If $t_{WCS} \geq t_{WCS(min)}$, the cycle is an EARLY WRITE cycle and the data output will remain an open circuit throughout the entire cycle. If $t_{RWD} \geq t_{RWD(min)}$, $t_{AWD} \geq t_{AWD(min)}$ and $t_{CWD} \geq t_{CWD(min)}$, the cycle is READ-WRITE and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until \overline{CAS} and \overline{RAS} or \overline{OE} go back to V_{IH}) is indeterminate. \overline{OE} held high and \overline{WE} taken low after \overline{CAS} goes low result in a LATE WRITE (\overline{OE} - controlled) cycle.
12. These parameters are referenced to \overline{CAS} leading edge in EARLY WRITE cycles and \overline{WE} leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
13. During a READ cycle, if \overline{OE} is low then taken HIGH before \overline{CAS} goes high, I/O goes open, if \overline{OE} is tied permanently low, a LATE WRITE or READ-MODIFY-WRITE operation is not possible.
14. An initial pause of 100ms is required after power-up followed by eight \overline{RAS} refresh cycles (\overline{RAS} only or CBR) before proper device operation is assured. The eight \overline{RAS} cycle wake-ups should be repeated any time the t_{REF} refresh requirement is exceeded.
15. WRITE command is defined as \overline{WE} going low.
16. LATE WRITE and READ-MODIFY-WRITE cycles must have both t_{OFF2} and t_{OEH} met (\overline{OE} high during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycles.
17. The I/Os open during READ cycles once t_{OFF1} or t_{OFF2} occur.
18. The first \overline{CAS} edge to transition low.
19. The last \overline{CAS} edge to transition high.
20. Output parameter (I/O) is referenced to corresponding \overline{CAS} input, IO1~8 by \overline{CASL} and IO9~16 by \overline{CASH} .
21. Last falling \overline{CAS} edge to first rising \overline{CAS} edge.
22. Last rising \overline{CAS} edge to next cycle's last rising \overline{CAS} edge.
23. Last rising \overline{CAS} edge to first falling \overline{CAS} edge.
24. First IOs controlled by the first \overline{CAS} to go low.
25. Last IOs controlled by the last \overline{CAS} to go high.
26. Each \overline{CAS} must meet minimum pulse width.
27. Last \overline{CAS} to go low.
28. All IOs controlled, regardless \overline{CASL} and \overline{CASH} .
29. Data outputs are measured with a load of 50pF. The output reference levels are $V_{OH}/V_{OL} = 2.0V/0.8V$; The input levels are $V_{IH}/V_{IL} = 3.0V/0V$.

READ CYCLE



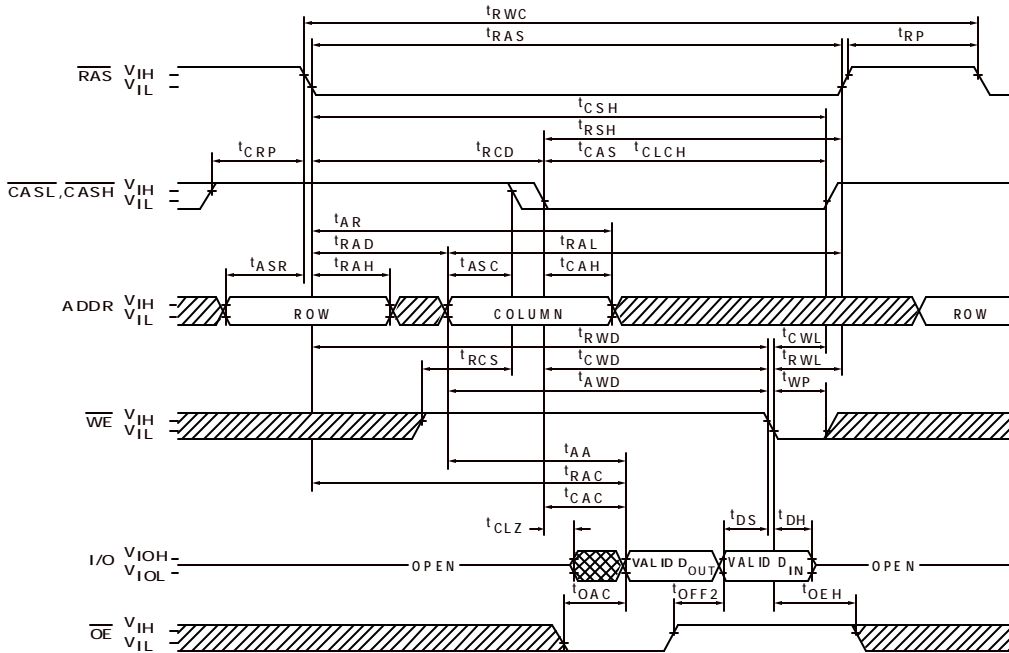
EARLY WRITE CYCLE



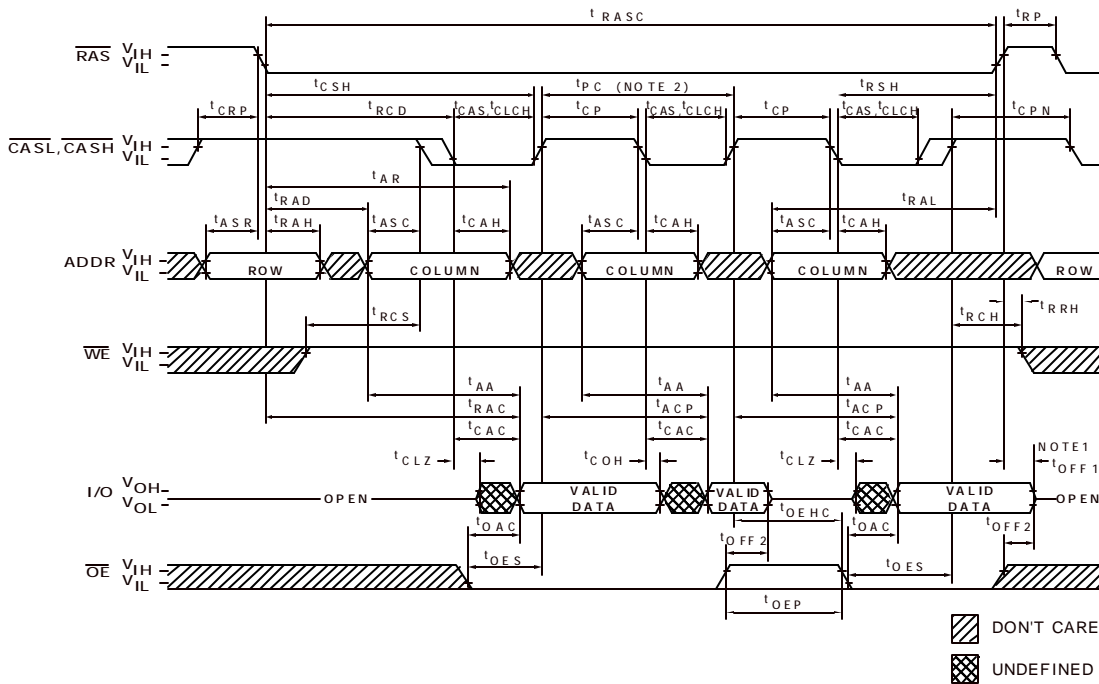
 DONT CARE
 UNDEFINED

Note: 1. t_{OFF1} is referenced from the rising edge of \overline{RAS} or \overline{CAS} , whichever occurs last.

READ WRITE CYCLE
(LATE WRITE and READ-MODIFY-WRITE CYCLES)

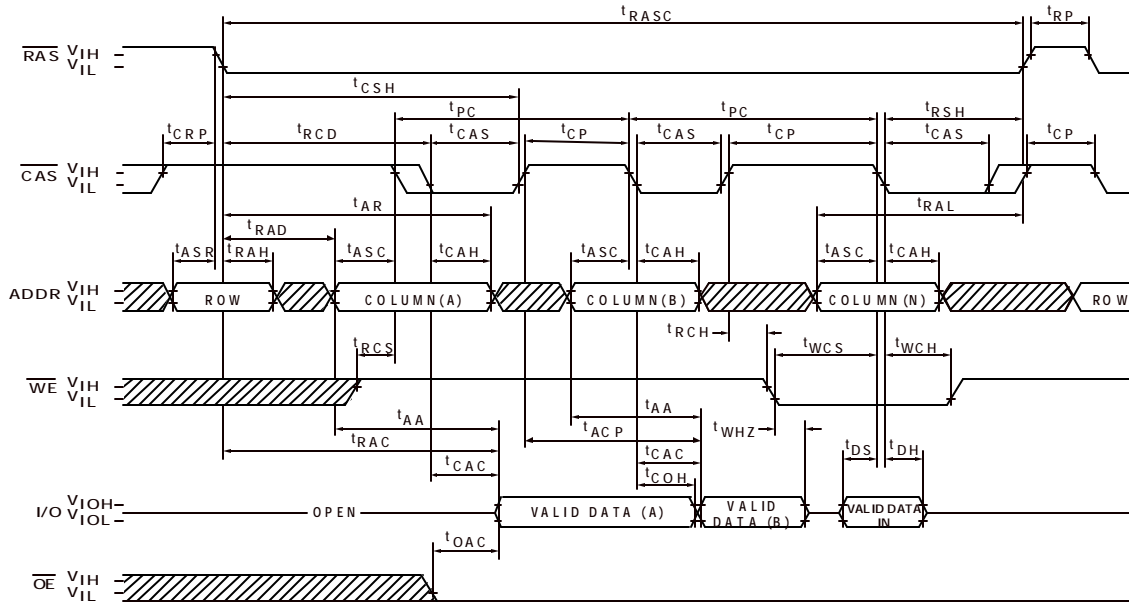


EDO-PAGE-MODE READ CYCLE

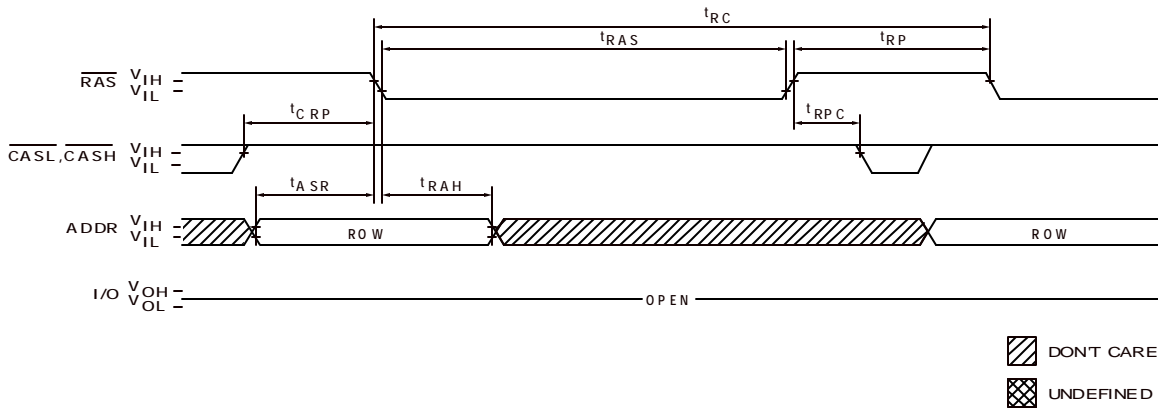


- Note:** 1. t_{OFF1} is referenced from the rising edge of \overline{RAS} or \overline{CAS} , whichever occurs last.
 2. t_{PC} can be measured from falling edge of \overline{CAS} to falling edge of \overline{CAS} , or from rising edge of \overline{CAS} to rising edge of \overline{RAS} . Both measurements must meet the t_{PC} specification.

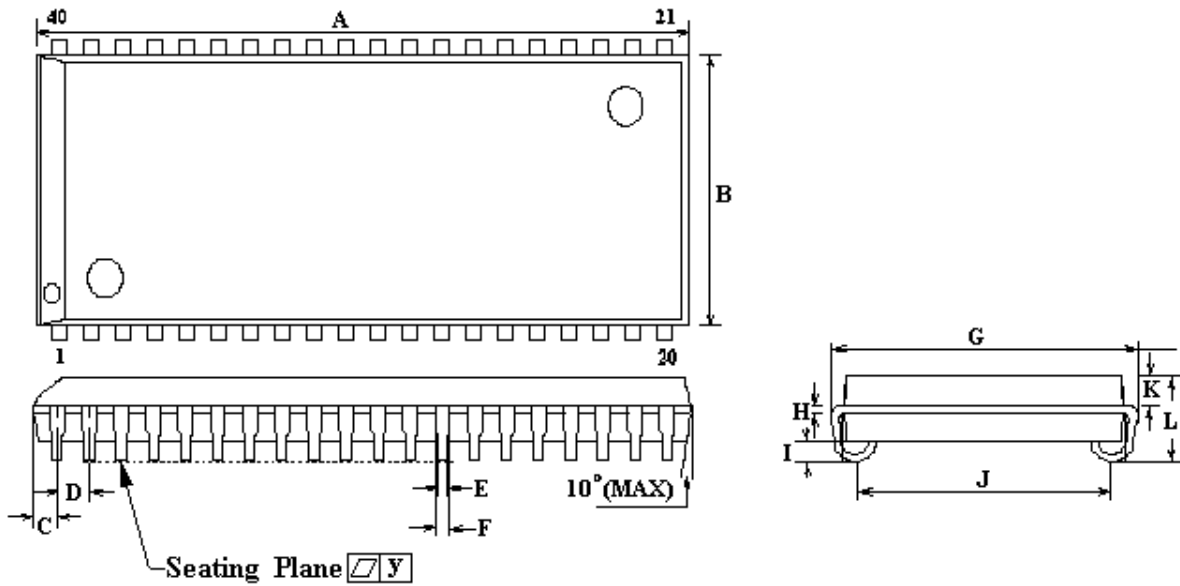
EDO-PAGE-MODE READ-EARLY-WRITE CYCLE
(Pseudo READ-MODIFY-WRITE)



RAS ONLY REFRESH CYCLE
(ADDR=A0-A8 ; OE, WE =DON'T CARE)

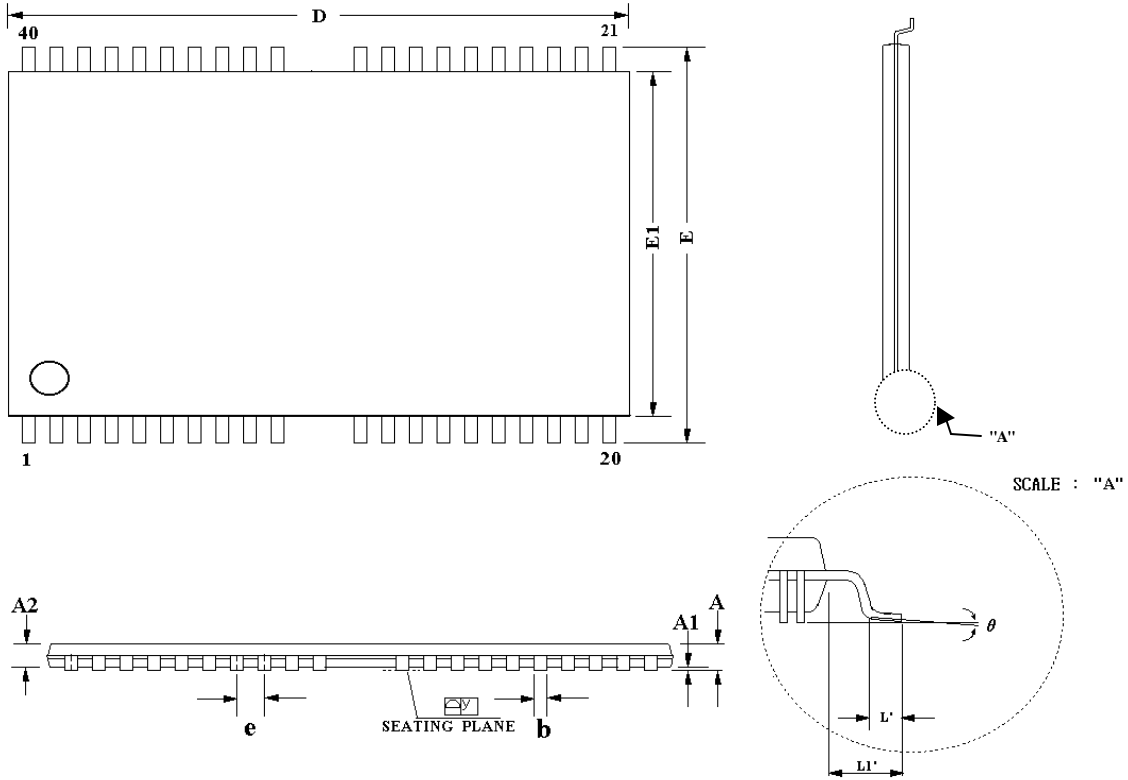


PACKAGE DIMENSIONS
40-LEAD SOJ DRAM (400 mil)



SYMBOL	DIMENSIONS IN INCHES	DIMENSIONS IN MM
A	1.025±0.010	26.035±0.254
B	0.400±0.005	10.160±0.127
C	0.045(MAX)	1.143(MAX)
D	0.050±0.006	1.27±0.152
E	0.019±0.003	0.483±0.08
F	0.026±0.003	0.661±0.080
G	0.440±0.010	11.176±0.254
H	0.011±0.003	0.280±0.080
I	0.025(MIN)	0.635(MIN)
J	0.364±0.020	9.246±0.508
K	0.047±0.006	1.194±0.152
L	0.150(MAX)	3.810(MAX)
y	0.004(MAX)	0.102(MAX)

PACKAGE DIMENSIONS
40-LEAD TSOP II DRAM (400 mil)



SYMBOL	DIMENSIONS IN INCHES	DIMENSIONS IN MM
A	0.047(max)	1.20(max)
A1	0.004±0.002	0.10±0.05
A2	0.039±0.002	1.00±0.05
b	0.014(typ.)	0.35(typ.)
e	0.030(typ.)	0.80(typ.)
D	0.725±0.004	18.41±0.10
E	0.463±0.008	11.76±0.20
E1	0.400±0.004	10.16±0.10
L1'	0.031	0.80
L'	0.020±0.004	0.500±0.10
y	0.004(max)	0.10(max)
θ	0°~5°	0°~5°